

DECLARATION FOR PATENT APPLICATION
(continuation page)

Invention title: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Inventor name(s) appearing on first declaration page: Chon Chin Hui

Additional original, first and joint inventor(s):

Full name of third joint inventor: Jason Pittam

Inventor's signature _____ Date _____

Residence: Morgan Hill, California

Citizenship: U.S.A.

Post Office Address: 16745 Barnell Avenue, Apt. 3, Morgan Hill, California 95037-4922